ABSTRACT

Support for semiconductor substrates for PECVD treatment with high substrate loading capacity

The present description concerns a support (54) for semiconductor substrates (26) comprising an assembly of trays (58A, 58B, 58C, 58D) having the semiconductor substrates resting thereon. Each tray is made of an electrically-conductive material and has at least one substantially vertical surface having locations arranged in at least two horizontally-oriented rows and two vertically-oriented columns. Each location receives a semiconductor substrate oriented with an inclination relative to a vertical direction varying from 1° to 10°. Each tray comprises, at each location, a recess or a cavity covered with the substrate (56). The trays of each pair of trays facing each other are separated by electrically-insulating spacers (60).

(Fig. 4)